

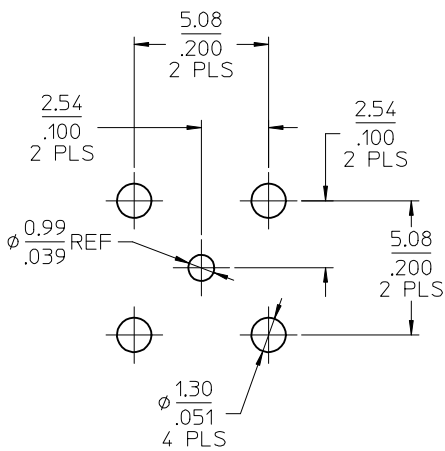
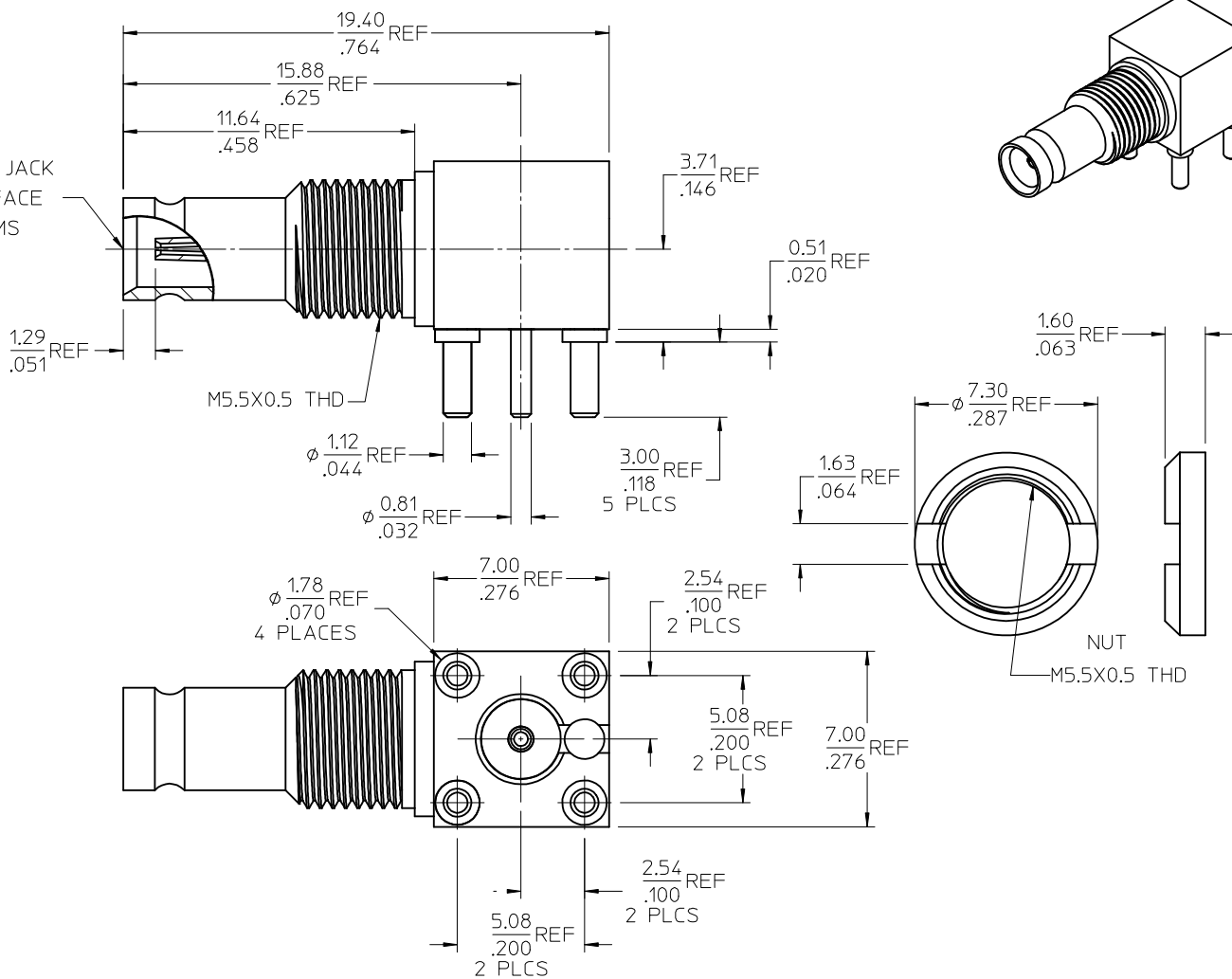
MATERIALS AND FINISHES

BODY, PIN, RETAINING RING, NUT: BRASS
PLATED: SEE TABLE

CONTACT: PHOSPHOR BRONZE
PLATED: GOLD (10μ-in MIN) OVER
NICKEL (100μ-in MIN)

INSULATOR: PTFE

1.0/2.3 JACK
INTERFACE
50 OHMS



RECOMMENDED HOLE LAYOUT

PS-89675-3450	PRODUCT SPECIFICATION
CECC 22 230	INTERFACE
SPECIFICATION	DESCRIPTION

73174-0411	GOLD (5μ-in MIN) OVER NICKEL (50μ-in MIN)
73174-0410	NICKEL (70μ-in MIN)
PART NO.	PLATING

CHG: UPDATE VIEWS FOR BODY AND POST CHANGES. ADD PLATING THICKNESS TO MATERIAL AND FINISH BLOCK/TABLE. ADD Ø1.78 4 PLACES DIM. ADD CUTAWAY VIEW AND 1.29 REF DIM. DEL MACHING NOTE.

EC NO: URF2017-0075
2016/08/09
DRW: MEIER
2016/08/10
CHKD: SSS
2016/08/16
APPR: ROBERTSON

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
▽=0	mm INCH
▽=0	4 PLACES ± --- ± ---
	3 PLACES ± --- ± ---
	2 PLACES ± --- ± ---
	1 PLACE ± --- ± ---
	ANGULAR ± 2 °

DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM/IN		METRIC	
DRAWN BY	DATE	TITLE	
SSS	2004/03/02	1.0/2.3 JACK, R/A PCB 50 OHMS, EWR-2361 1.0/2.3-J/PCB	
CHECKED BY	DATE	MOLEX INCORPORATED	
TEF	2004/03/02	MATERIAL NO. SEE TABLE	
APPROVED BY	DATE	DOCUMENT NO. SD-73174-041	
GMH	2004/03/02	SHEET NO. 1 OF 1	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

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